

## NCE P-Channel Enhancement Mode Power MOSFET

#### **Description**

The NCE60P05R uses advanced trench technology and design to provide excellent  $R_{\text{DS(ON)}}$  with low gate charge .This device is well suited for use as a load switch or in PWM applications.

#### **General Features**

•  $V_{DS} = -60V, I_{D} = -5A$ 

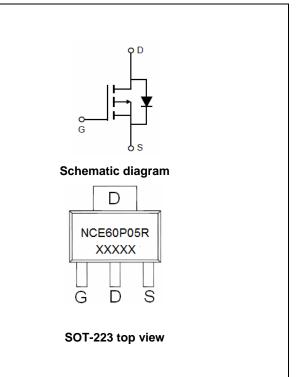
 $R_{DS(ON)}$  <65m $\Omega$  @  $V_{GS}$ =-10V

 $R_{DS(ON)}$  <85m $\Omega$  @  $V_{GS}$ =-4.5V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

## **Application**

- Load switch
- PWM application



## **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE60P05R	NCE60P05R	SOT-223-3L	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T<sub>C</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	-60	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	-5	А
Pulsed Drain Current	I <sub>DM</sub>	-20	Α
Maximum Power Dissipation	P <sub>D</sub>	3.1	W
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 To 150	$^{\circ}\mathbb{C}$

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{ heta JA}$	40.3	°C/W	l
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#### Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

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Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V,V <sub>GS</sub> =0V	-	-	-1	μΑ



## http://www.ncepower.com

# NCE60P05R

Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-1.0	-1.5	-2.0	V	
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-5A	-	55	65	mΩ	
Diain-Source On-State Resistance		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A	-	70	85	mΩ	
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-5V,I <sub>D</sub> =-5A	-	10	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C <sub>lss</sub>	\/ - 20\/\/ -0\/	-	1153	-	PF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =-30V, $V_{GS}$ =0V,		93.7	-	PF	
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	77.7	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t <sub>d(on)</sub>		-	8	-	nS	
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-30V, $R_L$ =6 $\Omega$ ,	-	5	-	nS	
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-10 $V$ , $R_{G}$ =3 $\Omega$	-	32	-	nS	
Turn-Off Fall Time	t <sub>f</sub>		-	8	-	nS	
Total Gate Charge	$Q_g$	V = 20.1 = 5A	-	15.8	-	nC	
Gate-Source Charge	Q <sub>gs</sub>		-	2.7	-	nC	
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =-10V	-	3.5	-	nC	
Drain-Source Diode Characteristics			•	•			
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-5A	-		-1.2	V	
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	-5	Α	
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> =- 5A	-	27		nS	
Reverse Recovery Charge	Qrr	$di/dt = -100A/\mu s^{(Note3)}$	-	32		nC	
Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge Drain-Source Diode Characteristics Diode Forward Voltage (Note 3) Diode Forward Current (Note 2) Reverse Recovery Time	$\begin{array}{c} t_{d(off)} \\ t_{f} \\ Q_{g} \\ Q_{gs} \\ Q_{gd} \\ \\ V_{SD} \\ I_{S} \\ t_{rr} \\ \end{array}$	$V_{GS}$ =-10V,R <sub>G</sub> =3 $\Omega$ $V_{DS}$ =-30,I <sub>D</sub> =-5A, $V_{GS}$ =-10V $V_{GS}$ =0V,I <sub>S</sub> =-5A	- - - -	32 8 15.8 2.7 3.5	- - - -	r r r	

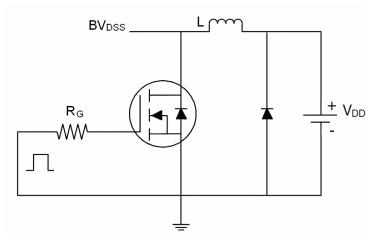
#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production

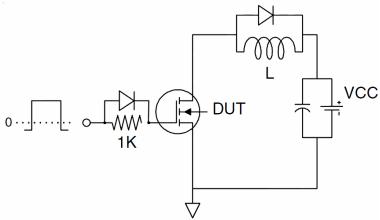


## **Test Circuit**

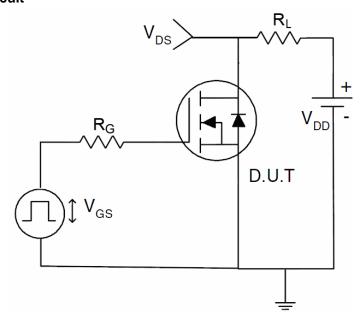
# 1) E<sub>AS</sub> test Circuit



# 2) Gate charge test Circuit

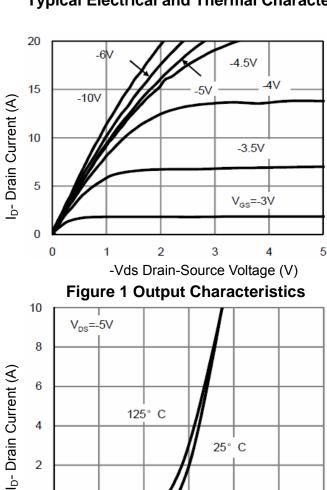


## 3) Switch Time Test Circuit





## **Typical Electrical and Thermal Characteristics (Curves)**



25° C 2 3 1 5 6 0 Vgs Gate-Source Voltage (V) **Figure 2 Transfer Characteristics** 

2

0

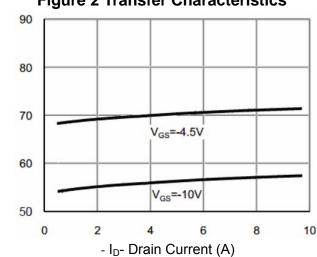
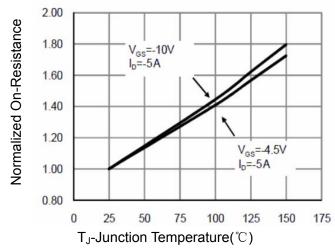
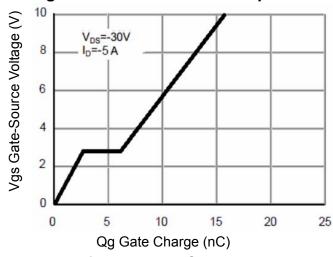


Figure 3 Rdson- Drain Current



**Figure 4 Rdson-Junction Temperature** 



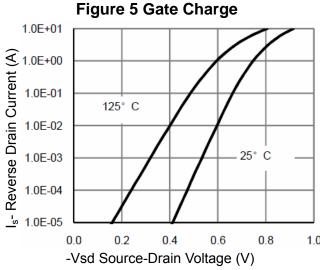


Figure 6 Source- Drain Diode Forward



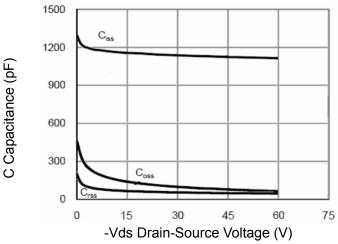
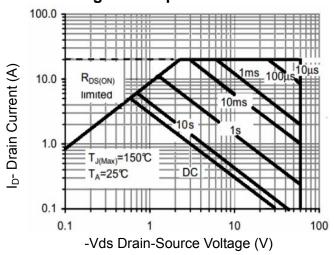


Figure 7 Capacitance vs Vds



**Figure 8 Safe Operation Area** 

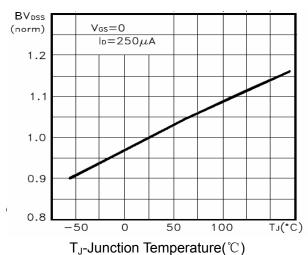


Figure 9 BV<sub>DSS</sub> vs Junction Temperature

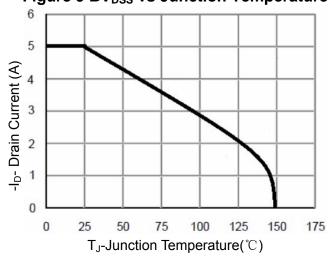
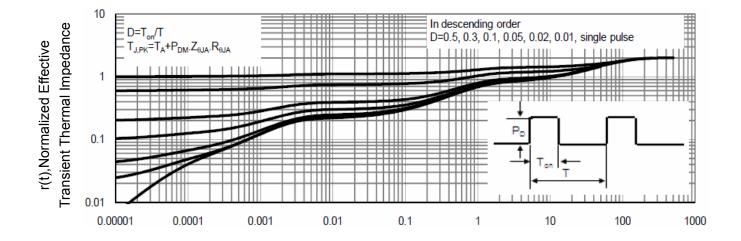


Figure 10 ID Current De-rating

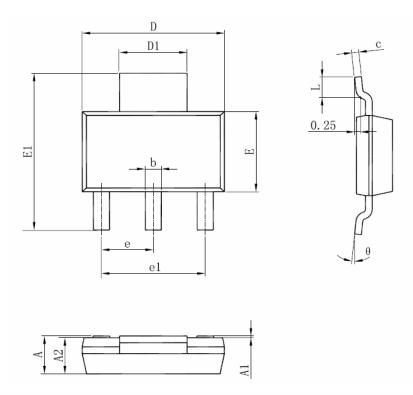


Square Wave Pluse Duration(sec)

**Figure 11 Normalized Maximum Transient Thermal Impedance** 



# **SOT-223 Package Information**

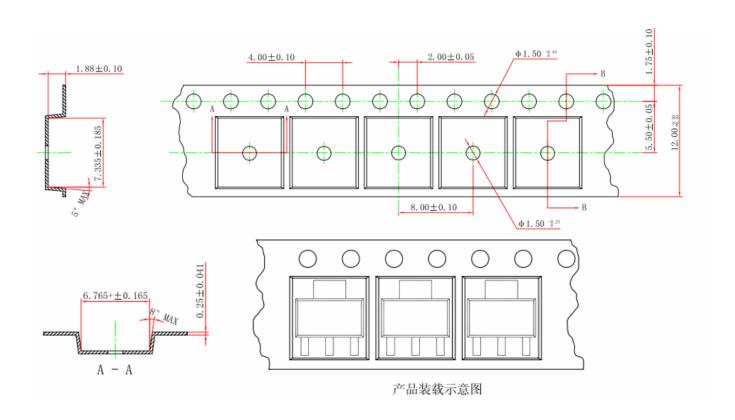


Comb o I	Dimensions Ir	n Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
Α	1.520	1.800	0.060	0.071
A1	0.000	0.100	0.000	0.004
A2	1.500	1.700	0.059	0.067
b	0.660	0.820	0.026	0.032
С	0.250	0.350	0.010	0.014
D	6.200	6.400	0.244	0.252
D1	2.900	3.100	0.114	0.122
E	3.300	3.700	0.130	0.146
E1	6.830	7.070	0.269	0.278
е	2.300	2.300(BSC)		BSC)
e1	4.500	4.700	0.177	0.185
L	0.900	1.150	0.035	0.045
θ	0°	10°	0°	10°

#### Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.





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